

## Press information

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## New black epoxy underfiller

**Panacol has developed a new epoxy-based underfiller. Structalit® 8202 is a low viscosity one-part adhesive with a high capillary flow filling the narrowest gaps.**

Structalit® 8202 is a high performance underfill material designed for chip stack packages and BGA. It is a one part, black colored epoxy with low viscosity which flows into the narrowest gaps. Special features of this product are its low coefficient of thermal expansion and high glass transition temperature. This makes Structalit® 8202 stable at high temperatures, allowing usage in reflow processes.

Structalit® 8202 cures rapidly under the influence of heat. The underfiller can also be cured during reflow processes. Due to its very good compatibility with most leadfree solders the adhesive cures completely even if it gets into contact with residues from flux agents.

Once cured, the material provides excellent mechanical properties to protect solder joints during thermal cycling. Structalit® 8202 is RoHS compliant and meets electronic grade standards (less than 900ppm Cl-).

### About Panacol:

Panacol-Elosol GmbH, a member of the global Hoenle group, is an international supplier of adhesives with an extensive product range that includes UV curable adhesives, structural adhesives, and conductive adhesives. Panacol is also a reliable provider of UV processing systems, supported by Dr. Hoenle AG. Hoenle is a global technology leader and manufacturer of industrial UV curing devices and systems.